

Discription

The HSTS232050UL40 protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect 2 unidirectional line in applications where arrays are not practical.

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Features

- ★ We declare that the material of product compliance with RoHS requirements and Halogen Free.
- ★ 2 unidirectionaltransilfunctions
- * Low leakage current:IR max< 20 μA at VRM
- ★ 300W peak pulse power(8/20µs)
- ★ Transient protection for data lines as per
- ★ IEC61000-4-2(ESD) 15KV(air) 8KV(contact)
- ★ IEC61000-4-5(Lightning) see IPPM below

Orderingin formation

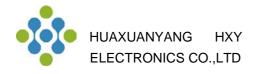
Product ID	Pack	Qty(PCS)
HSTS232050UL40	SOT-23	3000

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units	
P _{PP}	Peak Pulse Power (t _P = 8/20µs)	100	W	
TL	Maximum lead temperature for soldering during 10s	260	°C	
T _{stg}	Storage Temperature Range	-55 to +150	°C	
T _{op}	Operating Temperature Range		-40 to +125	°C
Tj	Maximum junction temperature		150	°C
		discharge discharge	土15 土8	KV

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Circuit Diagram



LICCTICAL CHARACTERISTICS Ratings at 25 C ambient temperature unless otherwise specified. VF = 0.9V at Ir = 1011A							
Device	V _{RWM} (V)	I _R (uA) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)	Ι _Τ	V _c (V) @ Max I _{PP} *	І _{РР} (А)*	C (pF)
	Max	Max	Min	mA	Мах	Мах	Тур
HSTS232050UL40	5	0.5	6	1	25	4	0.5

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

1. V_{BR} is measured with a pluse test current I_T at an ambient temperature of $25\,^\circ\!\!\mathbb{C}$.

Typical Characteristics

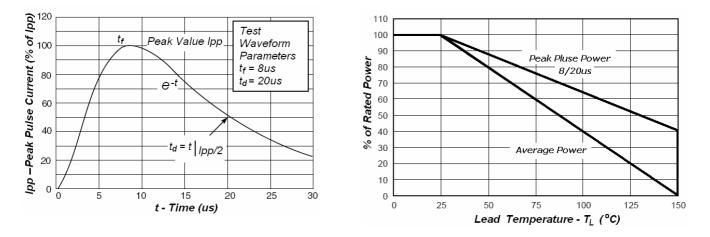
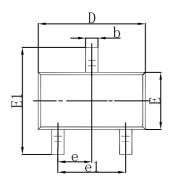


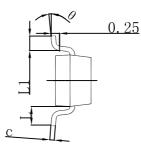
Fig 1. Pulse Waveform

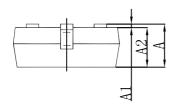
Fig 2.Power Derating



SOT-23 Package Outline Dimensions

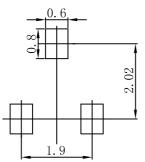






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037	' TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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